

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, emplo



FDBL0630N150

November 2014

N-Channel Power Trench[®] MOSFET 150V, 169A, $6.3 m\Omega$

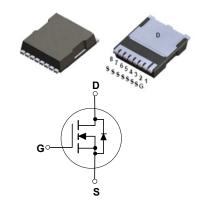
Features

- Typ $r_{DS(on)}$ = 5mΩ at V_{GS} = 10V, I_D = 80A
- Typ $Q_{q(tot)}$ = 70nC at V_{GS} = 10V, I_D = 80A
- UIS Capability
- RoHS Compliant

Applications

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





For current package drawing, please refer to the Fairchild website at https://www.fairchildsemi.com/evaluate/package-specifications/packageDetails.html?id=PN_PSOFA-008

MOSFET Maximum Ratings T_J = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain to Source Voltage		150	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	169	A
ID	Pulsed Drain Current	T _C = 25°C	See Figure4	_ A
E _{AS}	Single Pulse Avalanche Energy (Note 2)		502	mJ
D	Power Dissipation		500	W
P_D	Derate above 25°C		3.3	W/°C
T _J , T _{STG}	Operating and Storage Temperature	-55 to + 175	°C	
$R_{\theta JC}$	Thermal Resistance Junction to Case	0.3	°C/W	
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient	43	°C/W	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDBL0630N150	FDBL0630N150	MO-299A	-	-	-

Notes

- 1: Current is limited by junction temperature.
- 2: Starting $T_J = 25^{\circ}C$, L = 0.24mH, $I_{AS} = 64$ A, $V_{DD} = 100$ V during inductor charging and $V_{DD} = 0$ V during time in avalanche
- 3: $R_{\theta,JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta,JC}$ is guaranteed by design while $R_{\theta,JA}$ is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Units

Max

Тур

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Parameter

Off Characteristics							
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V$	_{'GS} = 0V	150	-	-	V
	Drain to Source Leakage Current	V _{DS} =150V,	$T_{J} = 25^{\circ}C$	-	-	1	μΑ
IDSS	Drain to Source Leakage Current	$V_{GS} = 0V$	$T_J = 175^{\circ}C(Note 4)$	-	-	1	mA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

Test Conditions

Min

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	2.8	4.0	V
r _{DS(on)} Drain to Source On Resistance	Drain to Source On Resistance	I _D = 80A,	$T_{J} = 25^{\circ}C$		5	6.3	$m\Omega$
	V _{GS} = 10V	$T_J = 175^{\circ}C(Note 4)$	-	14	17.5	mΩ	

Dynamic Characteristics

C _{iss}	Input Capacitance	75)/)/ 0)/		-	5805	-	pF
C _{oss}	Output Capacitance	— v _{DS} = 75v, v _{GS} = — f = 1MHz	$V_{DS} = 75V, V_{GS} = 0V,$		536	-	pF
C _{rss}	Reverse Transfer Capacitance	-		-	16	-	pF
R_g	Gate Resistance	f = 1MHz		-	2.2	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V _{GS} = 0 to 10V	V _{DD} = 75V	-	70	90	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0$ to 2V	I _D = 80A	-	10.5	13	nC
Q_{gs}	Gate to Source Gate Charge		_	-	32.5	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	10	-	nC

Switching Characteristics

t _{on}	Turn-On Time		-	-	80	ns
t _{d(on)}	Turn-On Delay Time		-	39	-	ns
t _r	Rise Time	V _{DD} = 75V, I _D = 80A,	-	30	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_{GEN} = 6\Omega$	-	70	-	ns
t _f	Fall Time		-	23	-	ns
t _{off}	Turn-Off Time		-	-	130	ns

Drain-Source Diode Characteristics

Ved Source to Drain Dioge Voltage	Source to Drain Diede Voltage	I _{SD} =80A, V _{GS} = 0V			1.25	V
	I_{SD} = 40A, V_{GS} = 0V	-	1	1.2	V	
T _{rr}	Reverse Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	108	125	ns
Q _{rr}	Reverse Recovery Charge	V _{DD} =120V	-	323	467	nC

Notes:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

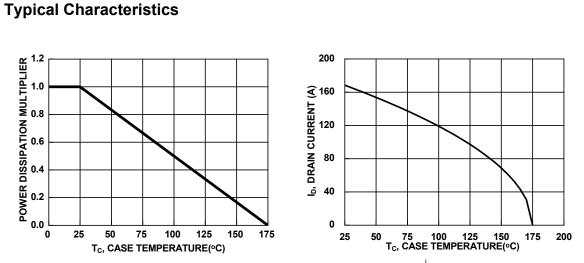
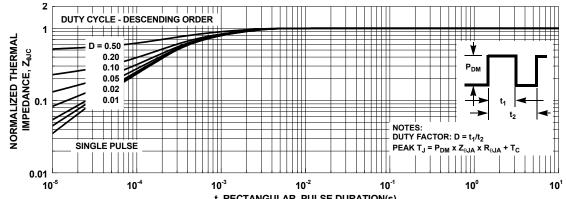


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

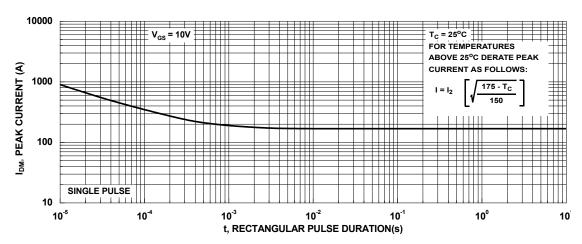


Figure 4. Peak Current Capability

Typical Characteristics

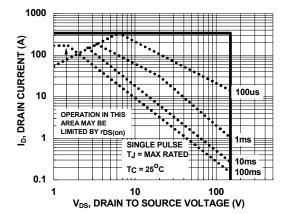
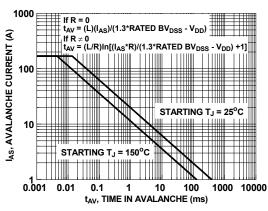


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability

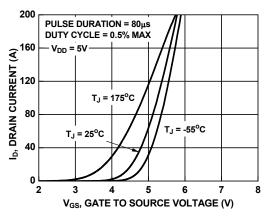


Figure 7. Transfer Characteristics

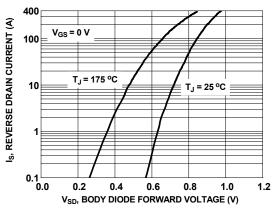


Figure 8. Forward Diode Characteristics

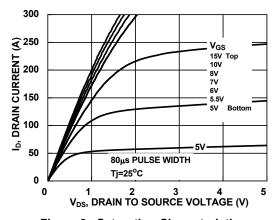


Figure 9. Saturation Characteristics

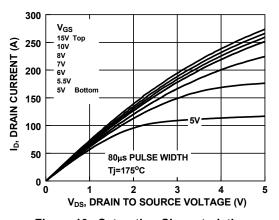


Figure 10. Saturation Characteristics

Typical Characteristics

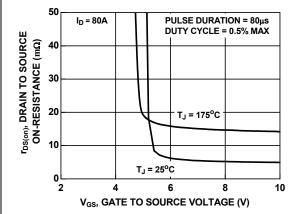


Figure 11. Rdson vs Gate Voltage

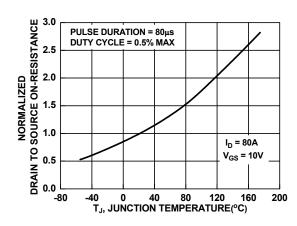


Figure 12. Normalized Rdson vs Junction Temperature

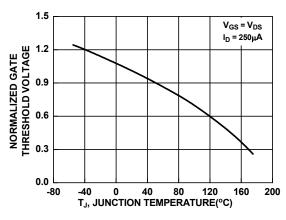


Figure 13. Normalized Gate Threshold Voltage vs
Temperature

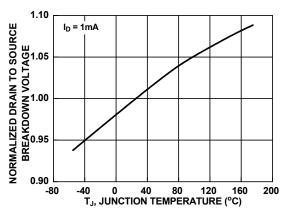


Figure 14. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

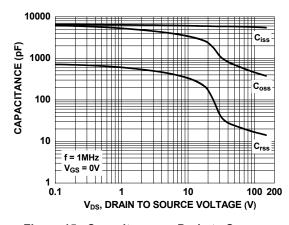


Figure 15. Capacitance vs Drain to Source Voltage

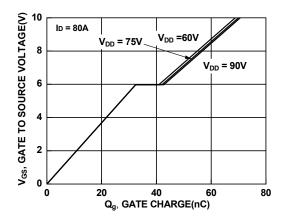


Figure 16. Gate Charge vs Gate to Source Voltage





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

 $(I)_{\mathbb{R}}$

AccuPower™
Awinda®
AX-CAP®*
BitSiC™
Build it Now™
CorePLUS™

CorePLUS™
CorePOWER™
CROSSVOLT™
CTL™
Current Transfer Logic™

DEUXPEED®

Dual Cool™

EcoSPARK®

EfficentMax™

ESBC™

Fairchild® Fairchild S FACT Qui

Fairchild Semiconductor®
FACT Quiet Series™
FACT®
FAST®
FastvCore™
FETBench™
FPS™

F-PFS™ FRFET® Global Power ResourceSM

GreenBridge™ Green FPS™ Green FPS™ e-Series™

GmaxTM
GTOTM
IntelliMAXTM
ISOPLANARTM
Marking Small 6

Marking Small Speakers Sound Louder and Better™

MegaBuck™
MICROCOUPLER™
MicroFET™
MicroPak™
MicroPak2™
MillerDrive™
MotionMax™

MotionGrid® MTi® MTx® MVN® mWSaver® OptoHiT™ PowerTrench[®] PowerXS™

Programmable Active Droop™

QFET[®]
QS™
Quiet Series™
RapidConfigure™

Saving our world, 1mW/W/kW at a time™ SignalWise™ SmartMax™

SMART START™ Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8

SupreMOS[®]
SyncFET™
Sync-Lock™

SYSTEM ®*
GENERAL
TinyBoost®
TinyBuck®
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyWire™
TranSiC™
TriFault Detect™
TRUECURRENT®*

Scropes*
UHC®
UHtra FRFET™
UniFET™
VCX™
VisualMax™
VoltagePlus™
XS™
Xsens™

μSerDes™

*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT http://www.fairchildsemi.com. Fairchild does not assume any Liability Arising out of the application or use of any product or circuit described herein; Neither does it convey any License under its patent rights, nor the rights of others. These specifications do not expand the terms of fairchild's worldwide terms and conditions, specifically the warranty therein, which covers these products.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used here in:

- Life support devices or systems are devices or systems which, (a) are
 intended for surgical implant into the body or (b) support or sustain life,
 and (c) whose failure to perform when properly used in accordance with
 instructions for use provided in the labeling, can be reasonably
 expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 171

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative